

MINUTES

P-2.5 COMMITTEE FOR TANTALUM & NIOBIUM CAPACITORS

WEDNESDAY, April 2, 2008
2:00 to 4:00 PM
Louisville, KY

1. COMMITTEE ORGANIZATION AND PROCEDURES

1.1 Membership and attendance

Membership and attendance taken. 6 of 6 companies represented.

1.2 Review and approve agenda

Agenda approved.

1.3 Approve minutes of last meeting, San Antonio, Sept, 2008

Minutes approved with corrections to the roster.

1.4 Correspondence

None

2. OLD BUSINESS

2.1 Reports

None

2.1.1 Passive Component Steering Committee (S.1).....Mike Lauri (Announcement of future meeting dates and locations)

Mike reported on activities from S-1 Committee Meeting from Apr 1. Next meeting is in Salt Lake City.

2.1.2 Government Specifications and Standards..... DSCC Representative

55365 is under revision with the G11. Dave Toomey is working with DSCC on the updates and has attended the G11 meeting.

2.2 Surface Mount Tantalum Capacitors

2.1 Status: Standard (EIA-535BAAC), Draft of new universal spec from Charlotte working group meeting.

Currently working on a universal spec to include SMD Ta, NbO, and solid Alum chips. Will include general, qualification, application. A nine page draft was initiated during a working group section in Charlotte, NC in November.

Ralph has recommended we send out a meeting summary from the Charlotte, NC meeting along with today's meeting minutes.

Next workshop meeting is scheduled for July 7th in Charlotte.

2.1.2 Discussion of new case sizes, ratings, or products....All Members

2.2 AEC Q 200 Preconditioning DOE project

2.4.1 Hi Temp (275C) requirement for new Joint Spec on Passive Component classification regarding lead-free soldering.

J-STD-075: Standard was discussed and confirmed that the proper exceptions were made in the latest revision of 075. So no changes recommended.

2.5 Update EIA 809 Tantalum Applications Guide

No updates. 809 will be captured in the new universal spec.

2.7 Review and update EIA list of "active working projects

The universal spec needs to have a PN. All other PNs will become non-active since the universal spec will cover all items.

3. **NEW BUSINESS**

3.1.1 Hi Temp (275C) requirement for new Joint Spec on Passive Component classification regarding lead-free soldering.

See 2.4.1

3.1.2 Recommendation for a component bulletin on voltage derating.

Dave purposed creating a bulletin to address confusion with voltage derating.

3.2 Inputs for "All-Chairs Meeting"

4. ADJOURNMENT